PNA4K01F

Bipolar Integrated Circuit with Photodetection Function

For brightness control systems

■ Features

- Peak sensitivity wavelength: 560 nm
- Output ratio of incandescent light and fluorescent light: 1.1 (typ.)
- Small, thin type package: $1.55 \text{ mm} \times 1.5 \text{ mm} \times 0.53 \text{ mm}$
- Surface-mouting type for reflow soldering

■ Absolute Maximum Ratings $T_a = 25$ °C

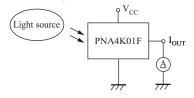
Parameter	Symbol	Rating	Unit	
Operating supply voltage	V _{CC}	-0.5 to $+7.0$	V	
Power dissipation	P _D	35	mW	
Operating ambient temperature	T _{opr}	-30 to +85	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

■ Electro-Optical Characteristics $T_a = 25$ °C±3°C, $V_{CC} = 3$ V

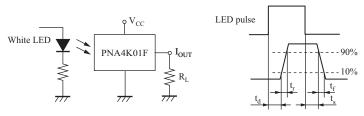
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Operating supply voltage	V _{CC}	91,2, 197.	1.4		5.5	V
Saturation voltage *3	V _{O(sat)}	$E_V = 100 \text{ lx}, R_L = 100 \text{ k}\Omega$	2.60	2.94	3.00	V
Supply current *1	I_{CC}	$E_V = 1000 \text{ lx}, R_L = 1 \text{ k}\Omega$	8	480	920	μΑ
Output current 1 *1, *3	I _{O1}	$E_V = 100 \text{ lx}$	29	48	90	μΑ
Output current 2 *2, *3	I _{O2}	$E_V = 10 lx$	2.5	4.3	7.9	μΑ
Output current 3 *2, *3	I_{O3}	$E_V = 100 \text{ lx}$	25	43	79	μΑ
Output current ratio	I _{O1} / I _{O3}	Jan Wall Floor Hall	30, 30	1.10	1.65	_
Drain current	I_D	$E_V = 0 lx$	No	10	100	nA
Peak sensitivity wavelength	λ_{PD}	18/18 1180 111	100	560		nm
Rise time *4	t _r	6. 2 11/10 11/0		30	1 000	μs
Fall time *4	$t_{\rm f}$	D = 51160		230	1000	μs
Delay time *4	t _d	$R_L = 5.1 \text{ k}\Omega$		110		μs
Storage time *4	t _s	112, 1/4/4		8		μs

Note) *1: Light source is CIE standard A light source. (Incandescent lamp)

- *2: Light source is fluorescence light.
- *3: Output current measurement circuit

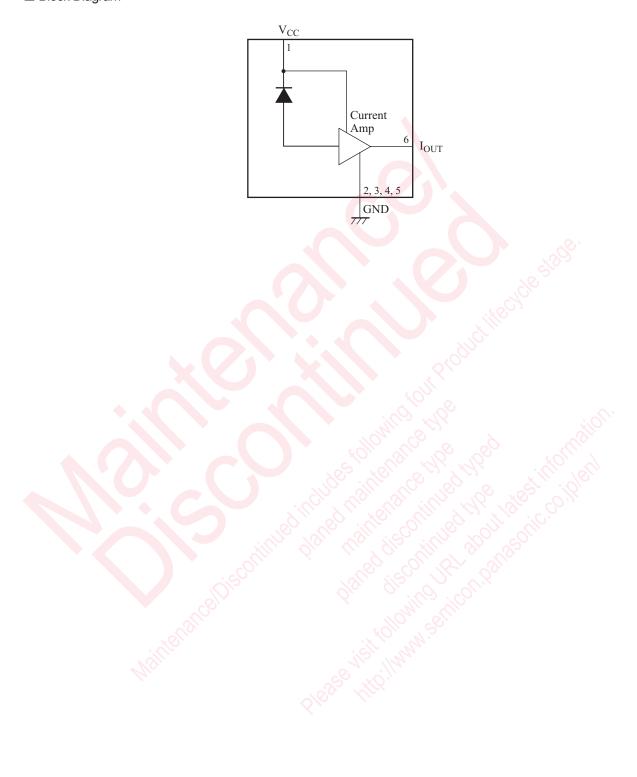


*4: Switching time measurement method



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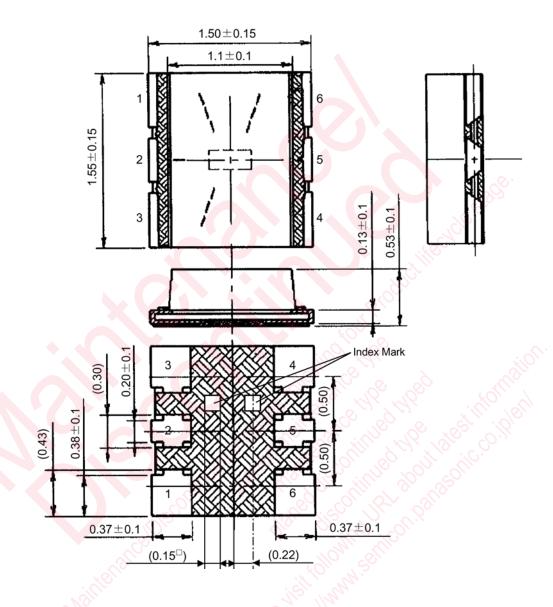
■ Block Diagram



Panasonic PNA4K01F

■ Package (Unit: mm)

KPTFTN6K0001



- Pin name
 - 1: V_{CC}
 - 2: GND
 - 3: GND
 - 4: GND
 - 5: GND
 - 6: I_{OUT}

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